

## TECHNOLOGY

**COATING:** EPOXY GLOB TOP / UV GLOB TOP  
SILICONE  
UNDERFILL  
FILLING MASS

**SUBSTRATES:** THICK FILM CERAMIC  
FR4, FR5, G10, G11, ROGERS  
FLEX, RIGID FLEX, IMS  
PYREX  
...

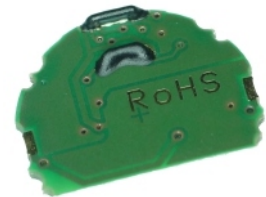
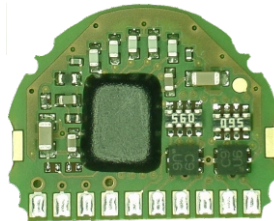
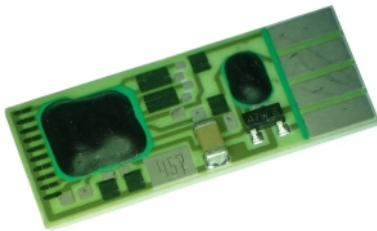
**COLORS:** TRANSPARENT  
OPAQUE  
BLACK  
...

**PROCESS:** MANUAL  
AUTOMATIC

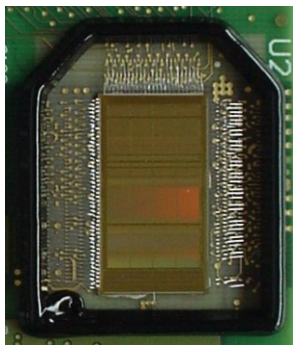
CHOOSING THE KIND OF RESIN AND THE MANUFACTURING PROCESS FOR THE MODULES' PROTECTION IS DEFINED IN COLLABORATION WITH THE CLIENT, ACCORDING TO THE PRODUCT SPECIFICATIONS.

## GLOB TOP TECHNIQUES

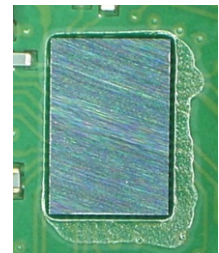
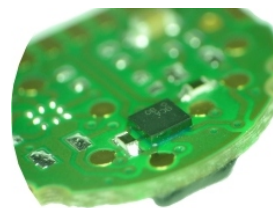
### COATING



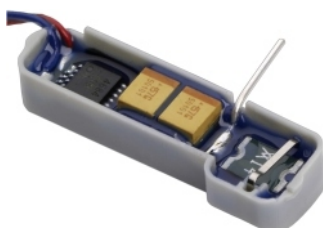
### DAM & FILL



### UNDERFILL (FLIP-CHIP, CSP, BGA)



### FILLING MASS (SUPPORT AND PROTECTION)



**HYBRID SA** IS ABLE TO PROTECT MICRO-ELECTRONIC MODULES ACCORDING TO SHAPE AS WELL AS MINIMUM AND MAXIMUM HEIGHT SPECIFICATIONS. QUALIFIED STAFF, AT TIMES ASSISTED BY DISPENSING ROBOTS, ABLE TO SATISFY THE MOST DEMANDING PRODUCT NEEDS.